



HSM Wire International, Inc

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SUPERIOR ESSEX BONDABLE MAGNET WIRE

Essex bondable wires are described by the basecoat and topcoat materials. For example, Polybondex® T indicates that the basecoat is Thermalex 200®. Polybondex® G indicates that the basecoat is GP/MR - 200®. The bondcoat is described by the letter M or S for epoxy or polyamide, respectively.

Essex Bondable Magnet Wire Insulations:

Product	Basecoat Polymer	Topcoat Polymer	Bondcoat Polymer	Thermal Rating	
				°C	(UL)
Soderbond® N/130 (SBDX/130)	Polyurethane	Nylon	Butvar	130°	(130°)
Soderbond® (SBDX)	Polyurethane	Nylon	Butvar	105°	N/A
Polybondex (PBX-T) Bond S	Polyester	N/A	Aromatic Polyamide	180°	(180°)
Polybondex (PBX-T) Bond M	Polyester	N/A	Epoxy	180°	(180°)
Polybondex (PBX-G) Bond S	Polyester	Amide-Imide	Aromatic Polyamide	180°	(180°)
Polybondex (PBX-G) Bond M	Polyester	Amide-Imide	Epoxy	180°	(180°)
Amide-Imide High Temp Bond	Amide-Imide	Amide-Imide	Proprietary	N/A	N/A

Soderbond N/130 (Soderon® Bond C) has a Soderon base with a butvar bondcoat. It is primarily intended for higher temperature applications where a solderable insulation is desired. The butvar bondcoat may be activated with denatured or isopropyl alcohol or by heating.

Soderbond N (Soderon® Bond C) has a Soderon base with a butvar bondcoat. It is primarily intended for low temperature applications where a Solderable insulation is desired. The butvar bondcoat may be activated with denatured or isopropyl alcohol or by heating.

Bond S is an aromatic polyamide that has higher bond strength at elevated temperatures than other bondcoats. It is not attacked by conventional solvents, but is activated by heat.

Bond M is an epoxy bond designed for use at temperatures not to exceed approximately 130°C. Bond Strengths up to 130°C are higher than with butvar. Solvents such as MEK can activate Bond M, but heat bonding is recommended.

High Temp Bond is a proprietary polymer that has the highest bond strength at elevated temperatures than other bondcoats. It is not attacked by conventional solvents, but is activated by heat.

** To be used as a guideline only. We thank Superior Essex for this information. **

For more information please go to <http://www.superioressex.com/>.

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